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"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	ARM® Cortex®-M3
Core Size	32-Bit Single-Core
Speed	120MHz
Connectivity	CANbus, I²C, IrDA, LINbus, MMC, SPI, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, I²S, LCD, POR, PWM, WDT
Number of I/O	51
Program Memory Size	768KB (768K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	132K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 16x12b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/stmicroelectronics/stm32f205rft6tr

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1 Introduction

This datasheet provides the description of the STM32F205xx and STM32F207xx lines of microcontrollers. For more details on the whole STMicroelectronics STM32 family, please refer to [Section 2.1: Full compatibility throughout the family](#).

The STM32F205xx and STM32F207xx datasheet should be read in conjunction with the STM32F20x/STM32F21x reference manual. They will be referred to as STM32F20x devices throughout the document.

For information on programming, erasing and protection of the internal Flash memory, please refer to the STM32F20x/STM32F21x Flash programming manual (PM0059).

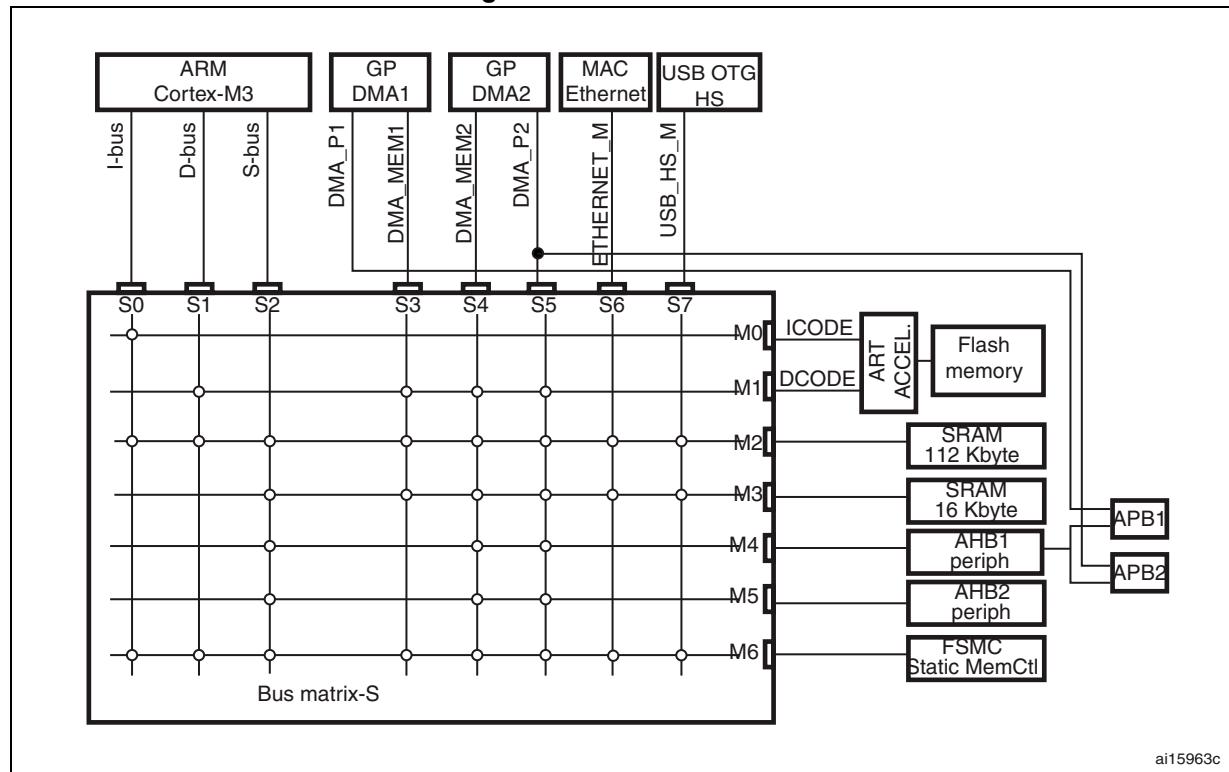
The reference and Flash programming manuals are both available from the STMicroelectronics website www.st.com.

For information on the Cortex®-M3 core please refer to the Cortex®-M3 Technical Reference Manual, available from the www.arm.com website.

Table 2. STM32F205xx features and peripheral counts

Peripherals		STM32F205Rx					STM32F205Vx					STM32F205Zx																					
Flash memory in Kbytes		128	256	512	768	1024	128	256	512	768	1024	256	512	768	1024																		
SRAM in Kbytes	System (SRAM1+SRAM2)	64 (48+16)	96 (80+16)	128 (112+16)			64 (48+16)	96 (80+16)	128 (112+16)			96 (80+16)	128 (112+16)																				
	Backup	4				4				4				4																			
FSMC memory controller		No					Yes ⁽¹⁾																										
Ethernet		No																															
Timers	General-purpose	10																															
	Advanced-control	2																															
	Basic	2																															
	IWDG	Yes																															
	WWDG	Yes																															
RTC		Yes																															
Random number generator		Yes																															
Comm. interfaces	SPI/(I ² S)	3/(2) ⁽²⁾																															
	I ² C	3																															
	USART UART	4 2																															
	USB OTG FS	Yes																															
	USB OTG HS	Yes																															
	CAN	2																															
Camera interface		No																															
GPIOs		51				82				114																							
SDIO		Yes																															
12-bit ADC Number of channels		3																															
		16				16				24																							
12-bit DAC Number of channels		Yes 2																															
	Maximum CPU frequency	120 MHz																															
Operating voltage		1.8 V to 3.6 V ⁽³⁾																															

Figure 5. Multi-AHB matrix

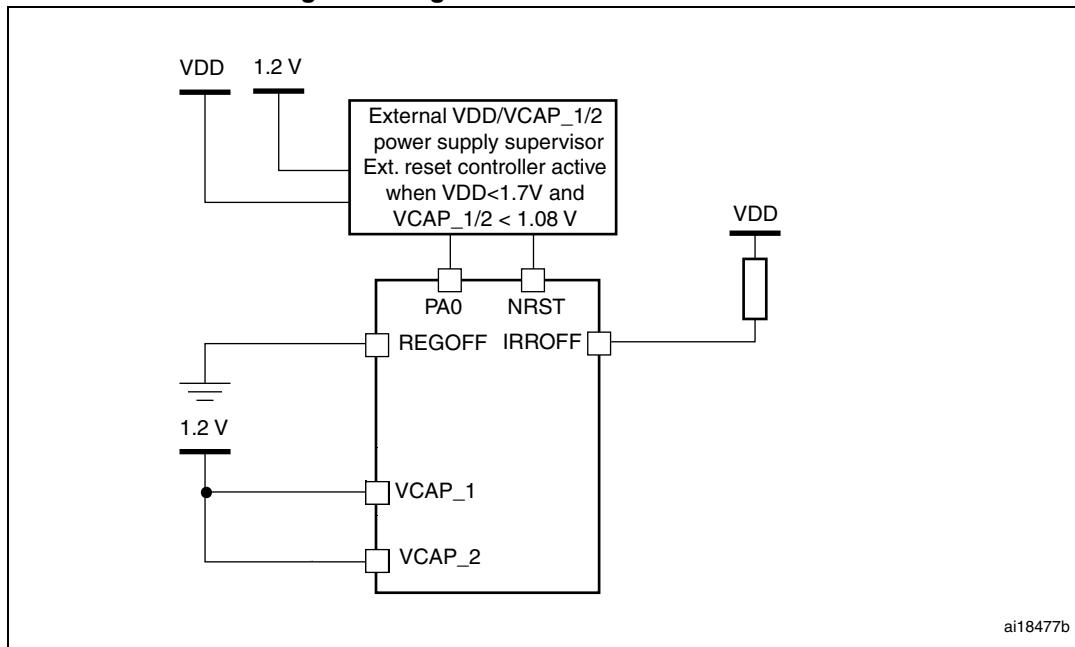


3.8 DMA controller (DMA)

The devices feature two general-purpose dual-port DMAs (DMA1 and DMA2) with 8 streams each. They are able to manage memory-to-memory, peripheral-to-memory and memory-to-peripheral transfers. They share some centralized FIFOs for APB/AHB peripherals, support burst transfer and are designed to provide the maximum peripheral bandwidth (AHB/APB).

The two DMA controllers support circular buffer management, so that no specific code is needed when the controller reaches the end of the buffer. The two DMA controllers also have a double buffering feature, which automates the use and switching of two memory buffers without requiring any special code.

Each stream is connected to dedicated hardware DMA requests, with support for software trigger on each stream. Configuration is made by software and transfer sizes between source and destination are independent.

Figure 7. Regulator OFF/internal reset OFF

The following conditions must be respected:

- V_{DD} should always be higher than V_{CAP_1} and V_{CAP_2} to avoid current injection between power domains (see [Figure 8](#)).
- PA0 should be kept low to cover both conditions: until V_{CAP_1} and V_{CAP_2} reach 1.08 V, and until V_{DD} reaches 1.7 V.
- NRST should be controlled by an external reset controller to keep the device under reset when V_{DD} is below 1.7 V (see [Figure 9](#)).

In this mode, when the internal reset is OFF, the following integrated features are no more supported:

- The integrated power-on reset (POR) / power-down reset (PDR) circuitry is disabled.
- The brownout reset (BOR) circuitry is disabled.
- The embedded programmable voltage detector (PWD) is disabled.
- V_{BAT} functionality is no more available and V_{BAT} pin should be connected to VDD.

If configured as standard 16-bit timers, they have the same features as the general-purpose TIMx timers. If configured as 16-bit PWM generators, they have full modulation capability (0-100%).

The TIM1 and TIM8 counters can be frozen in debug mode. Many of the advanced-control timer features are shared with those of the standard TIMx timers which have the same architecture. The advanced-control timer can therefore work together with the TIMx timers via the Timer Link feature for synchronization or event chaining.

3.20.2 General-purpose timers (TIMx)

There are ten synchronizable general-purpose timers embedded in the STM32F20x devices (see [Table 5](#) for differences).

TIM2, TIM3, TIM4, TIM5

The STM32F20x include 4 full-featured general-purpose timers. TIM2 and TIM5 are 32-bit timers, and TIM3 and TIM4 are 16-bit timers. The TIM2 and TIM5 timers are based on a 32-bit auto-reload up/downcounter and a 16-bit prescaler. The TIM3 and TIM4 timers are based on a 16-bit auto-reload up/downcounter and a 16-bit prescaler. They all feature 4 independent channels for input capture/output compare, PWM or one-pulse mode output. This gives up to 16 input capture/output compare/PWMs on the largest packages.

The TIM2, TIM3, TIM4, TIM5 general-purpose timers can work together, or with the other general-purpose timers and the advanced-control timers TIM1 and TIM8 via the Timer Link feature for synchronization or event chaining.

The counters of TIM2, TIM3, TIM4, TIM5 can be frozen in debug mode. Any of these general-purpose timers can be used to generate PWM outputs.

TIM2, TIM3, TIM4, TIM5 all have independent DMA request generation. They are capable of handling quadrature (incremental) encoder signals and the digital outputs from 1 to 4 hall-effect sensors.

TIM10, TIM11 and TIM9

These timers are based on a 16-bit auto-reload upcounter and a 16-bit prescaler. TIM10 and TIM11 feature one independent channel, whereas TIM9 has two independent channels for input capture/output compare, PWM or one-pulse mode output. They can be synchronized with the TIM2, TIM3, TIM4, TIM5 full-featured general-purpose timers. They can also be used as simple time bases.

TIM12, TIM13 and TIM14

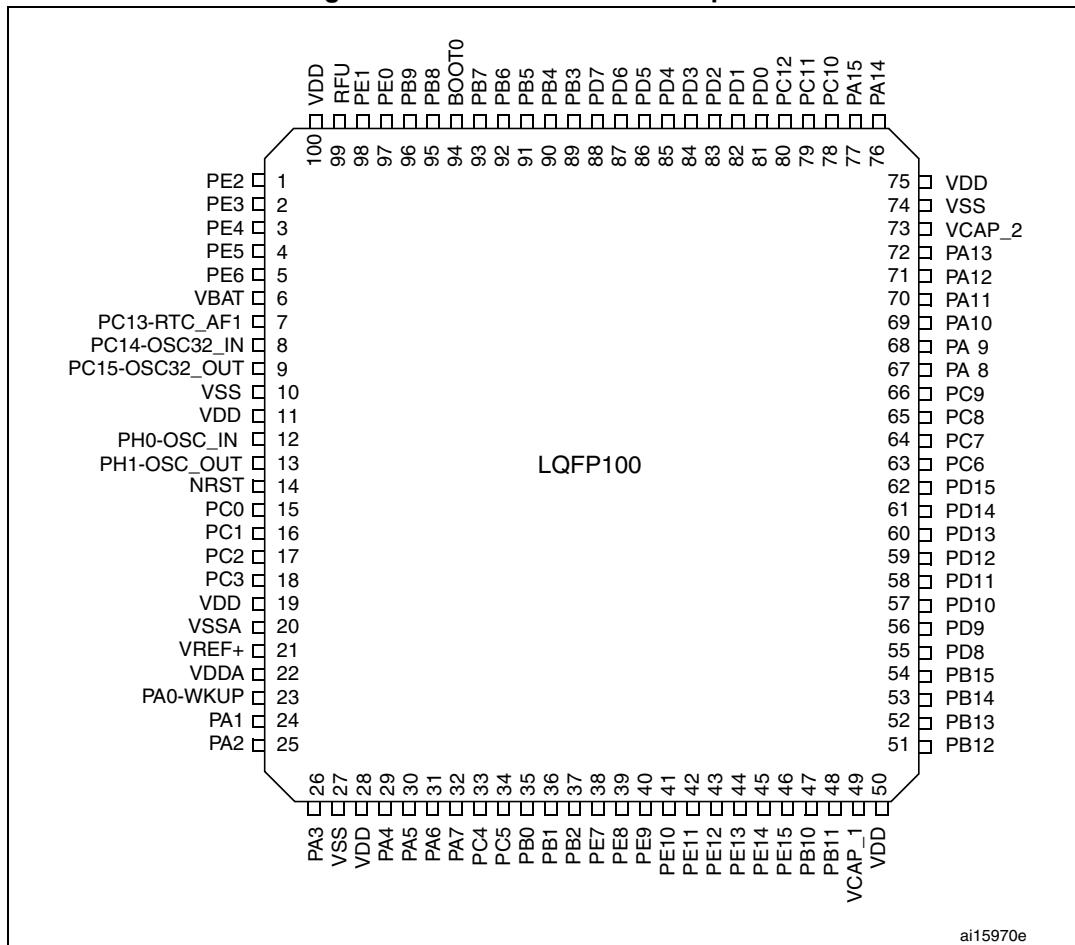
These timers are based on a 16-bit auto-reload upcounter and a 16-bit prescaler. TIM13 and TIM14 feature one independent channel, whereas TIM12 has two independent channels for input capture/output compare, PWM or one-pulse mode output. They can be synchronized with the TIM2, TIM3, TIM4, TIM5 full-featured general-purpose timers.

They can also be used as simple time bases.

3.20.3 Basic timers TIM6 and TIM7

These timers are mainly used for DAC trigger and waveform generation. They can also be used as a generic 16-bit time base.

Figure 12. STM32F20x LQFP100 pinout



1. RFU means "reserved for future use". This pin can be tied to V_{DD}, V_{SS} or left unconnected.
2. The above figure shows the package top view.

Table 10. Alternate function mapping (continued)

Port	AF0	AF1	AF2	AF3	AF4	AF5	AF6	AF7	AF8	AF9	AF10	AF11	AF12	AF13	AF014	AF15
	SYS	TIM1/2	TIM3/4/5	TIM8/9/10/11	I2C1/I2C2/I2C3	SPI1/SPI2/I2S2	SPI3/I2S3	USART1/2/3	UART4/5/ USART6	CAN1/CAN2/ TIM12/13/14	OTG_FS/ OTG_HS	ETH	FSMC/SDIO/ OTG_HS	DCMI		
Port F	PF0	-	-	-	-	I2C2_SDA	-	-	-	-	-	-	FSMC_A0	-	-	EVENTOUT
	PF1	-	-	-	-	I2C2_SCL	-	-	-	-	-	-	FSMC_A1	-	-	EVENTOUT
	PF2	-	-	-	-	I2C2_SMBA	-	-	-	-	-	-	FSMC_A2	-	-	EVENTOUT
	PF3	-	-	-	-	-	-	-	-	-	-	-	FSMC_A3	-	-	EVENTOUT
	PF4	-	-	-	-	-	-	-	-	-	-	-	FSMC_A4	-	-	EVENTOUT
	PF5	-	-	-	-	-	-	-	-	-	-	-	FSMC_A5	-	-	EVENTOUT
	PF6	-	-	-	TIM10_CH1	-	-	-	-	-	-	-	FSMC_NIORD	-	-	EVENTOUT
	PF7	-	-	-	TIM11_CH1	-	-	-	-	-	-	-	FSMC_NREG	-	-	EVENTOUT
	PF8	-	-	-	-	-	-	-	-	TIM13_CH1	-	-	FSMC_NIOWR	-	-	EVENTOUT
	PF9	-	-	-	-	-	-	-	-	TIM14_CH1	-	-	FSMC_CD	-	-	EVENTOUT
	PF10	-	-	-	-	-	-	-	-	-	-	-	FSMC_INTR	-	-	EVENTOUT
	PF11	-	-	-	-	-	-	-	-	-	-	-	DCMI_D12	-	-	EVENTOUT
	PF12	-	-	-	-	-	-	-	-	-	-	-	FSMC_A6	-	-	EVENTOUT
	PF13	-	-	-	-	-	-	-	-	-	-	-	FSMC_A7	-	-	EVENTOUT
	PF14	-	-	-	-	-	-	-	-	-	-	-	FSMC_A8	-	-	EVENTOUT
	PF15	-	-	-	-	-	-	-	-	-	-	-	FSMC_A9	-	-	EVENTOUT
Port G	PG0	-	-	-	-	-	-	-	-	-	-	-	FSMC_A10	-	-	EVENTOUT
	PG1	-	-	-	-	-	-	-	-	-	-	-	FSMC_A11	-	-	EVENTOUT
	PG2	-	-	-	-	-	-	-	-	-	-	-	FSMC_A12	-	-	EVENTOUT
	PG3	-	-	-	-	-	-	-	-	-	-	-	FSMC_A13	-	-	EVENTOUT
	PG4	-	-	-	-	-	-	-	-	-	-	-	FSMC_A14	-	-	EVENTOUT
	PG5	-	-	-	-	-	-	-	-	-	-	-	FSMC_A15	-	-	EVENTOUT
	PG6	-	-	-	-	-	-	-	-	-	-	-	FSMC_INT2	-	-	EVENTOUT
	PG7	-	-	-	-	-	-	-	-	USART6_CK	-	-	FSMC_INT3	-	-	EVENTOUT
	PG8	-	-	-	-	-	-	-	-	USART6 RTS	-	-	ETH_PPS_OUT	-	-	EVENTOUT
	PG9	-	-	-	-	-	-	-	-	USART6_RX	-	-	FSMC_NE2/ FSMC_NCE3	-	-	EVENTOUT
	PG10	-	-	-	-	-	-	-	-	-	-	-	FSMC_NCE4_1/ FSMC_NE3	-	-	EVENTOUT
	PG11	-	-	-	-	-	-	-	-	-	-	-	ETH_MII_TX_EN ETH_RMII_TXD0	FSMC_NCE4_2	-	EVENTOUT
	PG12	-	-	-	-	-	-	-	-	USART6 RTS	-	-	-	FSMC_NE4	-	EVENTOUT
	PG13	-	-	-	-	-	-	-	-	UART6_CTS	-	-	ETH_MII_TXD0 ETH_RMII_TXD0	FSMC_A24	-	EVENTOUT
	PG14	-	-	-	-	-	-	-	-	USART6 TX	-	-	ETH_MII_TXD1 ETH_RMII_TXD1	FSMC_A25	-	EVENTOUT
	PG15	-	-	-	-	-	-	-	-	USART6 CTS	-	-	-	DCMI_D13	-	EVENTOUT

Figure 16. Memory map

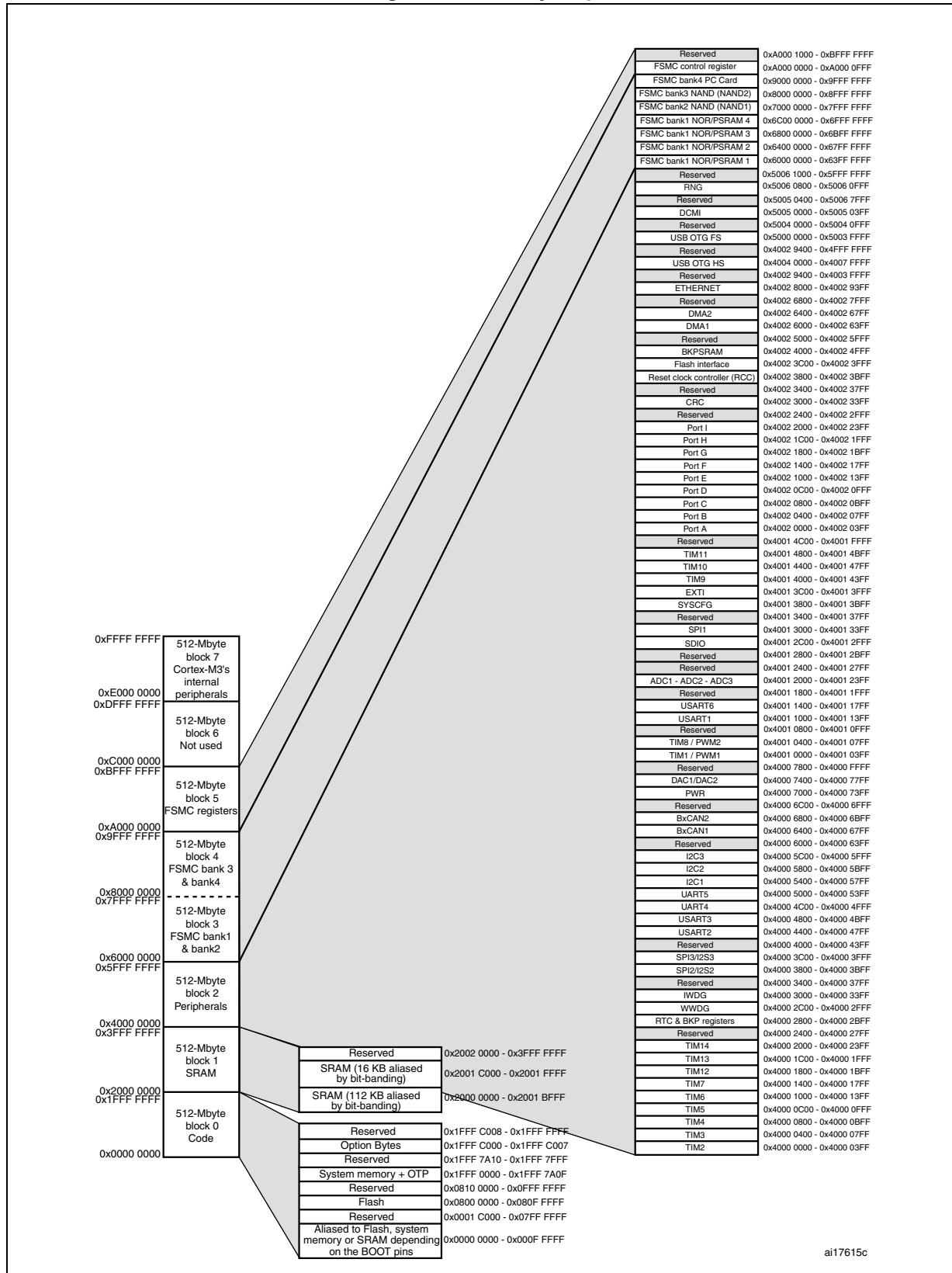


Table 15. Limitations depending on the operating power supply range

Operating power supply range	ADC operation	Maximum Flash memory access frequency (f_{Flashmax})	Number of wait states at maximum CPU frequency ($f_{\text{CPUmax}} = 120 \text{ MHz}$)⁽¹⁾	I/O operation	FSMC_CLK frequency for synchronous accesses	Possible Flash memory operations
$V_{\text{DD}} = 1.8 \text{ to } 2.1 \text{ V}^{(2)}$	Conversion time up to 1 Msps	16 MHz with no Flash memory wait state	7 ⁽³⁾	<ul style="list-style-type: none"> – Degraded speed performance – No I/O compensation 	Up to 30 MHz	8-bit erase and program operations only
$V_{\text{DD}} = 2.1 \text{ to } 2.4 \text{ V}$	Conversion time up to 1 Msps	18 MHz with no Flash memory wait state	6 ⁽³⁾	<ul style="list-style-type: none"> – Degraded speed performance – No I/O compensation 	Up to 30 MHz	16-bit erase and program operations
$V_{\text{DD}} = 2.4 \text{ to } 2.7 \text{ V}$	Conversion time up to 2 Msps	24 MHz with no Flash memory wait state	4 ⁽³⁾	<ul style="list-style-type: none"> – Degraded speed performance – I/O compensation works 	Up to 48 MHz	16-bit erase and program operations
$V_{\text{DD}} = 2.7 \text{ to } 3.6 \text{ V}^{(4)}$	Conversion time up to 2 Msps	30 MHz with no Flash memory wait state	3 ⁽³⁾	<ul style="list-style-type: none"> – Full-speed operation – I/O compensation works 	<ul style="list-style-type: none"> – Up to 60 MHz when $V_{\text{DD}} = 3.0 \text{ to } 3.6 \text{ V}$ – Up to 48 MHz when $V_{\text{DD}} = 2.7 \text{ to } 3.0 \text{ V}$ 	32-bit erase and program operations

1. The number of wait states can be reduced by reducing the CPU frequency (see [Figure 21](#)).
2. On devices in WLCSP64+2 package, if IRROFF is set to V_{DD} , the supply voltage can drop to 1.7 V when the device operates in the 0 to 70 °C temperature range using an external power supply supervisor (see [Section 3.16](#)).
3. Thanks to the ART accelerator and the 128-bit Flash memory, the number of wait states given here does not impact the execution speed from Flash memory since the ART accelerator allows to achieve a performance equivalent to 0 wait state program execution.
4. The voltage range for OTG USB FS can drop down to 2.7 V. However it is degraded between 2.7 and 3 V.

Table 26. Peripheral current consumption (continued)

Peripheral ⁽¹⁾	Typical consumption at 25 °C	Unit
APB2	SDIO	0.69
	TIM1	1.06
	TIM8	1.03
	TIM9	0.58
	TIM10	0.37
	TIM11	0.39
	ADC1 ⁽⁴⁾	2.13
	ADC2 ⁽⁴⁾	2.04
	ADC3 ⁽⁴⁾	2.12
	SPI1	1.20
	USART1	0.38
	USART6	0.37

1. External clock is 25 MHz (HSE oscillator with 25 MHz crystal) and PLL is on.
2. EN1 bit is set in DAC_CR register.
3. EN2 bit is set in DAC_CR register.
4. $f_{ADC} = f_{PCLK2}/2$, ADON bit set in ADC_CR2 register.

6.3.7 Wakeup time from low-power mode

The wakeup times given in [Table 27](#) is measured on a wakeup phase with a 16 MHz HSI RC oscillator. The clock source used to wake up the device depends from the current operating mode:

- Stop or Standby mode: the clock source is the RC oscillator
- Sleep mode: the clock source is the clock that was set before entering Sleep mode.

All timings are derived from tests performed under ambient temperature and V_{DD} supply voltage conditions summarized in [Table 14](#).

Table 27. Low-power mode wakeup timings

Symbol	Parameter	Min ⁽¹⁾	Typ ⁽¹⁾	Max ⁽¹⁾	Unit
$t_{WUSLEEP}^{(2)}$	Wakeup from Sleep mode	-	1	-	μs
$t_{WUSTOP}^{(2)}$	Wakeup from Stop mode (regulator in Run mode)	-	13	-	μs
	Wakeup from Stop mode (regulator in low-power mode)	-	17	40	
	Wakeup from Stop mode (regulator in low-power mode and Flash memory in Deep power down mode)	-	110	-	
$t_{WUSTDBY}^{(2)(3)}$	Wakeup from Standby mode	260	375	480	μs

1. Guaranteed by characterization results, not tested in production.
2. The wakeup times are measured from the wakeup event to the point in which the application code reads the first instruction.
3. $t_{WUSTDBY}$ minimum and maximum values are given at 105 °C and -45 °C, respectively.

Electromagnetic Interference (EMI)

The electromagnetic field emitted by the device are monitored while a simple application, executing EEMBC® code, is running. This emission test is compliant with SAE IEC61967-2 standard which specifies the test board and the pin loading.

Table 42. EMI characteristics

Symbol	Parameter	Conditions	Monitored frequency band	Max vs. [f _{HSE} /f _{CPU}]		Unit	
				25/120 MHz			
S _{EMI}	Peak level	V _{DD} = 3.3 V, T _A = 25 °C, LQFP176 package, conforming to SAE J1752/3 EEMBC, code running with ART enabled, peripheral clock disabled	0.1 to 30 MHz	25	dB μ V	dB μ V	
			30 to 130 MHz				
			130 MHz to 1GHz				
		SAE EMI Level	4				
	Peak level	V _{DD} = 3.3 V, T _A = 25 °C, LQFP176 package, conforming to SAE J1752/3 EEMBC, code running with ART enabled, PLL spread spectrum enabled, peripheral clock disabled	0.1 to 30 MHz	28	dB μ V		
			30 to 130 MHz	26			
			130 MHz to 1GHz	22			
		SAE EMI level	4				

6.3.14 Absolute maximum ratings (electrical sensitivity)

Based on three different tests (ESD, LU) using specific measurement methods, the device is stressed in order to determine its performance in terms of electrical sensitivity.

Electrostatic discharge (ESD)

Electrostatic discharges (a positive then a negative pulse separated by 1 second) are applied to the pins of each sample according to each pin combination. The sample size depends on the number of supply pins in the device (3 parts × (n+1) supply pins). This test conforms to the JESD22-A114/C101 standard.

Table 43. ESD absolute maximum ratings

Symbol	Ratings	Conditions	Class	Maximum value ⁽¹⁾	Unit
V _{ESD(HBM)}	Electrostatic discharge voltage (human body model)	T _A = +25 °C conforming to JESD22-A114	2	2000 ⁽²⁾	V
V _{ESD(CDM)}	Electrostatic discharge voltage (charge device model)	T _A = +25 °C conforming to JESD22-C101		500	

1. Guaranteed by characterization results, not tested in production.

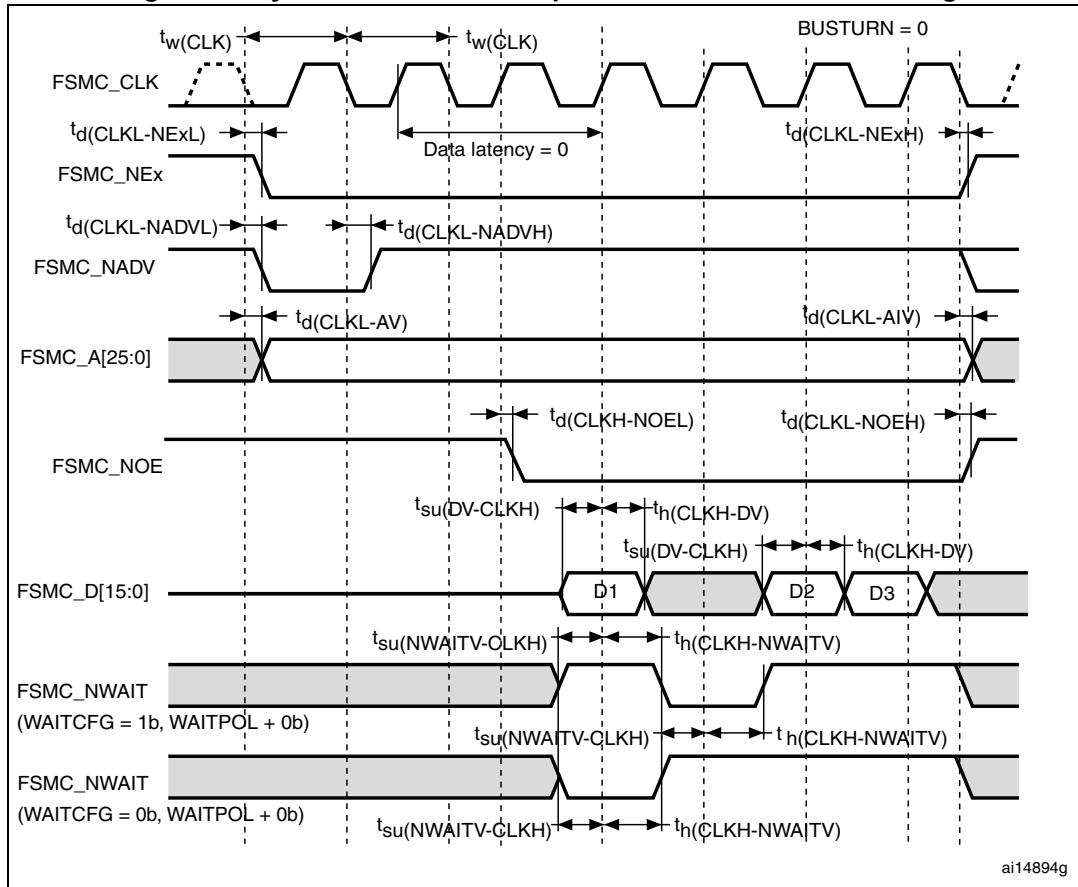
2. On V_{BAT} pin, V_{ESD(HBM)} is limited to 1000 V.

Table 77. Synchronous multiplexed PSRAM write timings⁽¹⁾⁽²⁾ (continued)

Symbol	Parameter	Min	Max	Unit
$t_d(CLKL-NWEL)$	FSMC_CLK low to FSMC_NWE low	-	1	ns
$t_d(CLKL-NWEH)$	FSMC_CLK low to FSMC_NWE high	0	-	ns
$t_d(CLKL-ADIV)$	FSMC_CLK low to FSMC_AD[15:0] invalid	0	-	ns
$t_d(CLKL-DATA)$	FSMC_A/D[15:0] valid data after FSMC_CLK low	-	2	ns
$t_d(CLKL-NBLH)$	FSMC_CLK low to FSMC_NBL high	0.5	-	ns

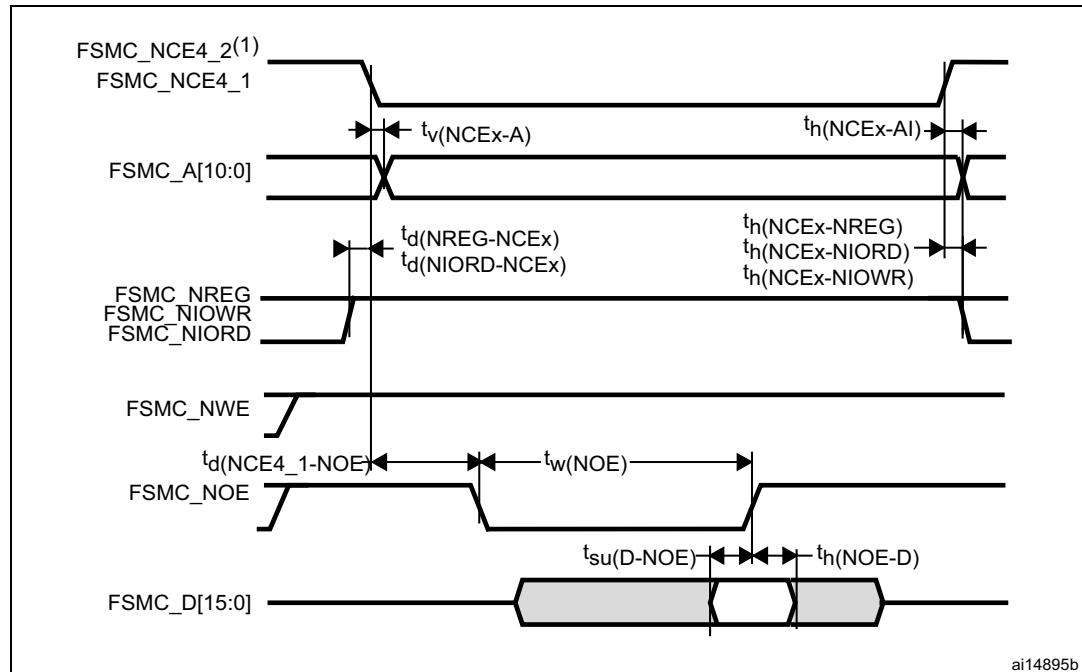
1. $C_L = 30 \text{ pF}$.

2. Guaranteed by characterization results, not tested in production.

Figure 63. Synchronous non-multiplexed NOR/PSRAM read timings**Table 78. Synchronous non-multiplexed NOR/PSRAM read timings⁽¹⁾⁽²⁾**

Symbol	Parameter	Min	Max	Unit
$t_w(CLK)$	FSMC_CLK period	$2T_{HCLK}$	-	ns
$t_d(CLKL-NExL)$	FSMC_CLK low to FSMC_NEx low ($x=0..2$)	-	0	ns
$t_d(CLKL-NExH)$	FSMC_CLK low to FSMC_NEx high ($x=0..2$)	1	-	ns
$t_d(CLKL-NADVL)$	FSMC_CLK low to FSMC_NADV low	-	2.5	ns

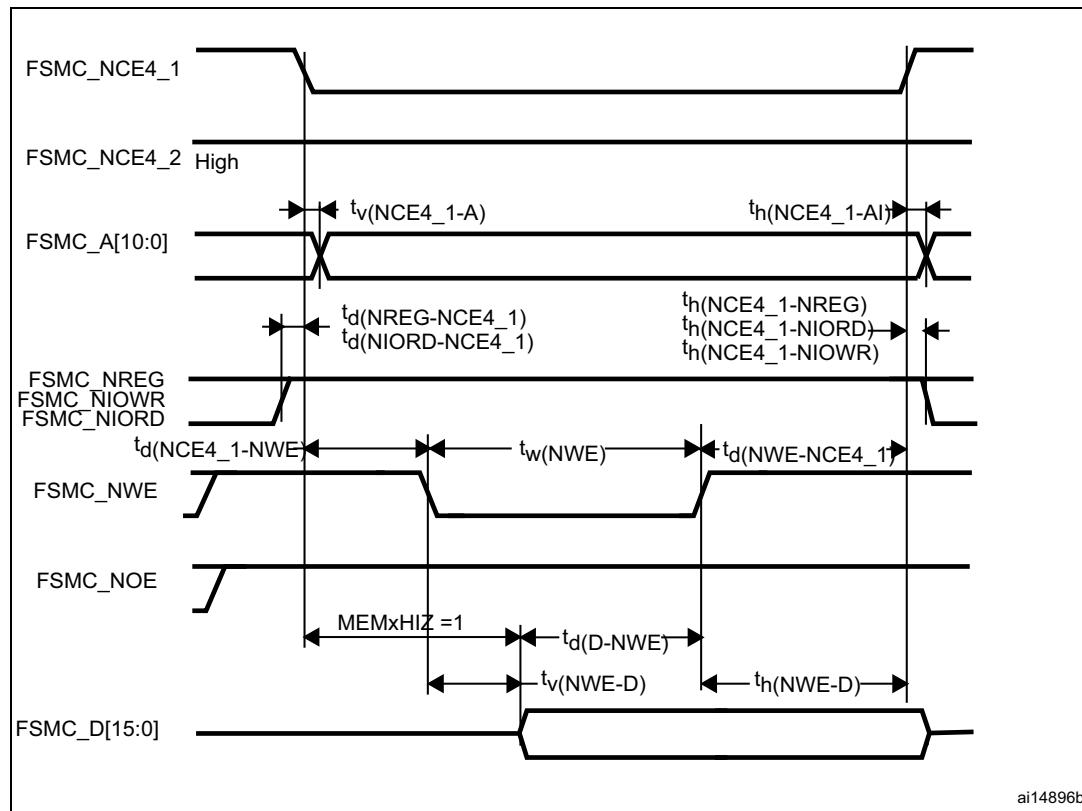
Figure 65. PC Card/CompactFlash controller waveforms for common memory read access



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1. FSMC_NCE4_2 remains high (inactive during 8-bit access).

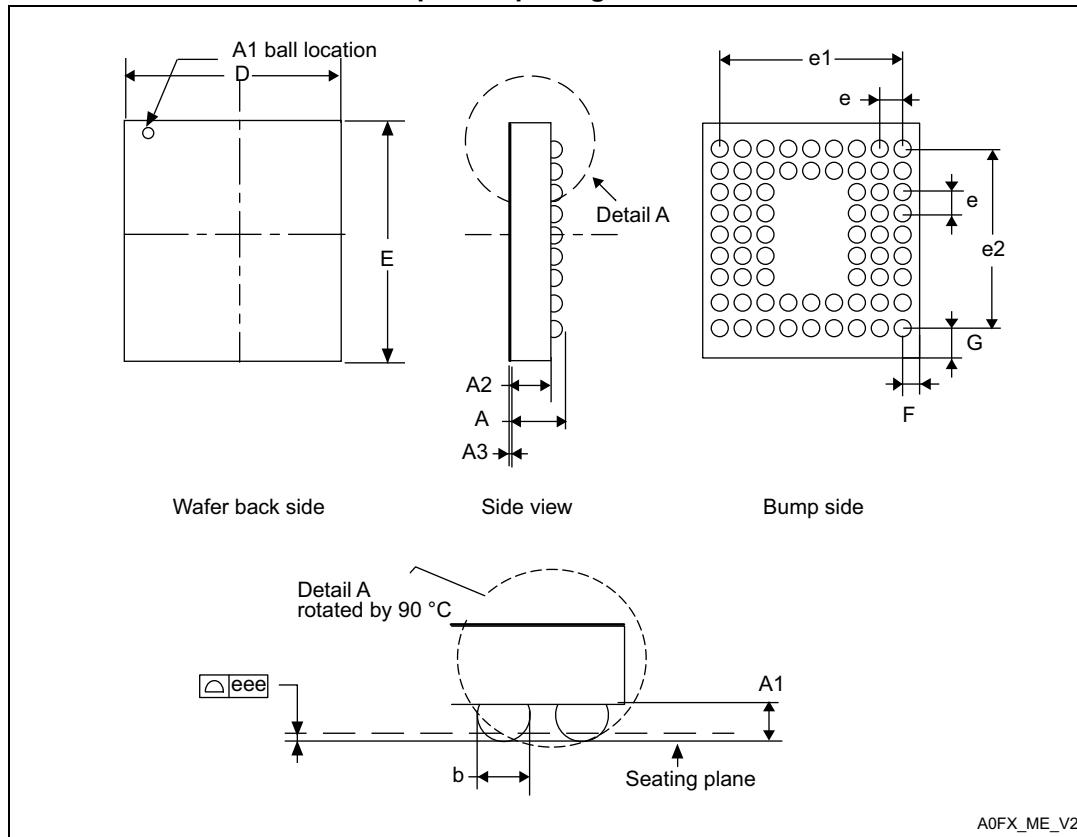
Figure 66. PC Card/CompactFlash controller waveforms for common memory write access



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7.2 WLCSP64+2 package information

Figure 79. WLCSP64+2 - 66-ball, 3.639 x 3.971 mm, 0.4 mm pitch wafer level chip scale package outline



1. Drawing is not to scale.

Table 88. WLCSP64+2 - 66-ball, 4.539 x 4.911 mm, 0.4 mm pitch wafer level chip scale package mechanical data

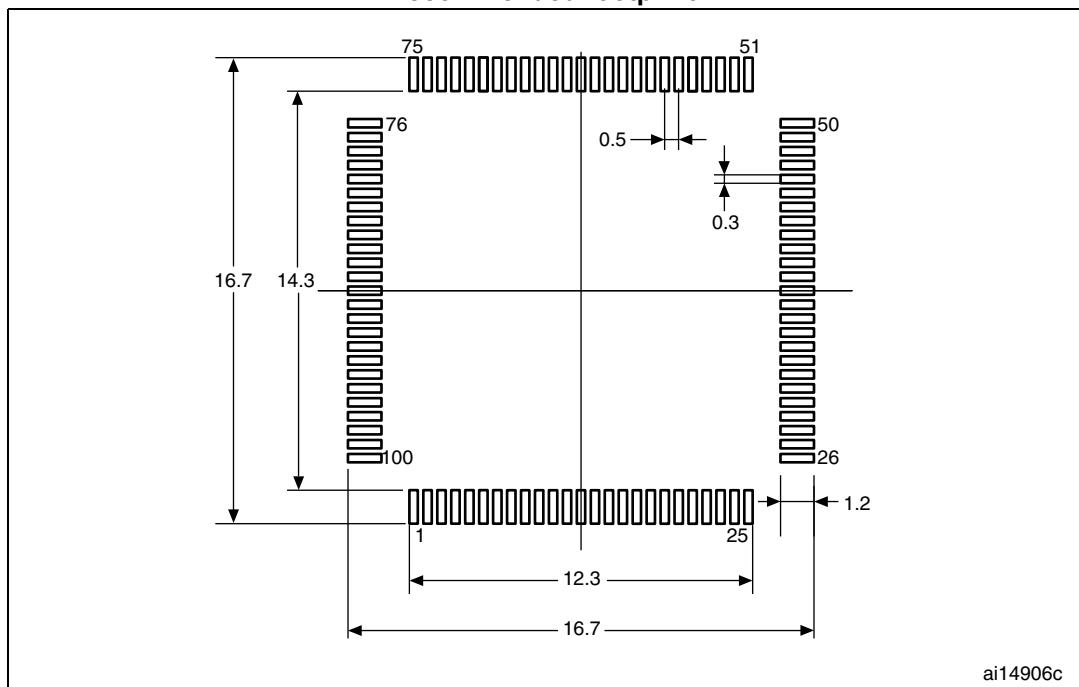
Symbol	millimeters			inches ⁽¹⁾		
	Min	Typ	Max	Min	Typ	Max
A	0.540	0.570	0.600	0.0213	0.0224	0.0236
A1	-	0.190	-	-	0.0075	-
A2	-	0.380	-	-	0.0150	-
A3	-	0.025	-	-	0.010	-
b ⁽²⁾	0.240	0.270	0.300	0.0094	0.0106	0.0118
D	3.604	3.939	3.674	0.1419	0.1551	0.1446
E	3.936	3.971	4.006	0.1550	0.1563	0.1577
e	-	0.400	-	-	0.0157	-
e1	-	3.200	-	-	0.1260	-
e2	-	3.200	-	-	0.1260	-

Table 90. LQPF100 - 100-pin, 14 x 14 mm low-profile quad flat package mechanical data (continued)

Symbol	millimeters			inches ⁽¹⁾		
	Min	Typ	Max	Min	Typ	Max
D3	-	12.000	-	-	0.4724	-
E	15.800	16.000	16.200	0.6220	0.6299	0.6378
E1	13.800	14.000	14.200	0.5433	0.5512	0.5591
E3	-	12.000	-	-	0.4724	-
e	-	0.500	-	-	0.0197	-
L	0.450	0.600	0.750	0.0177	0.0236	0.0295
L1	-	1.000	-	-	0.0394	-
k	0.0°	3.5°	7.0°	0.0°	3.5°	7.0°
ccc	-	-	0.080	-	-	0.0031

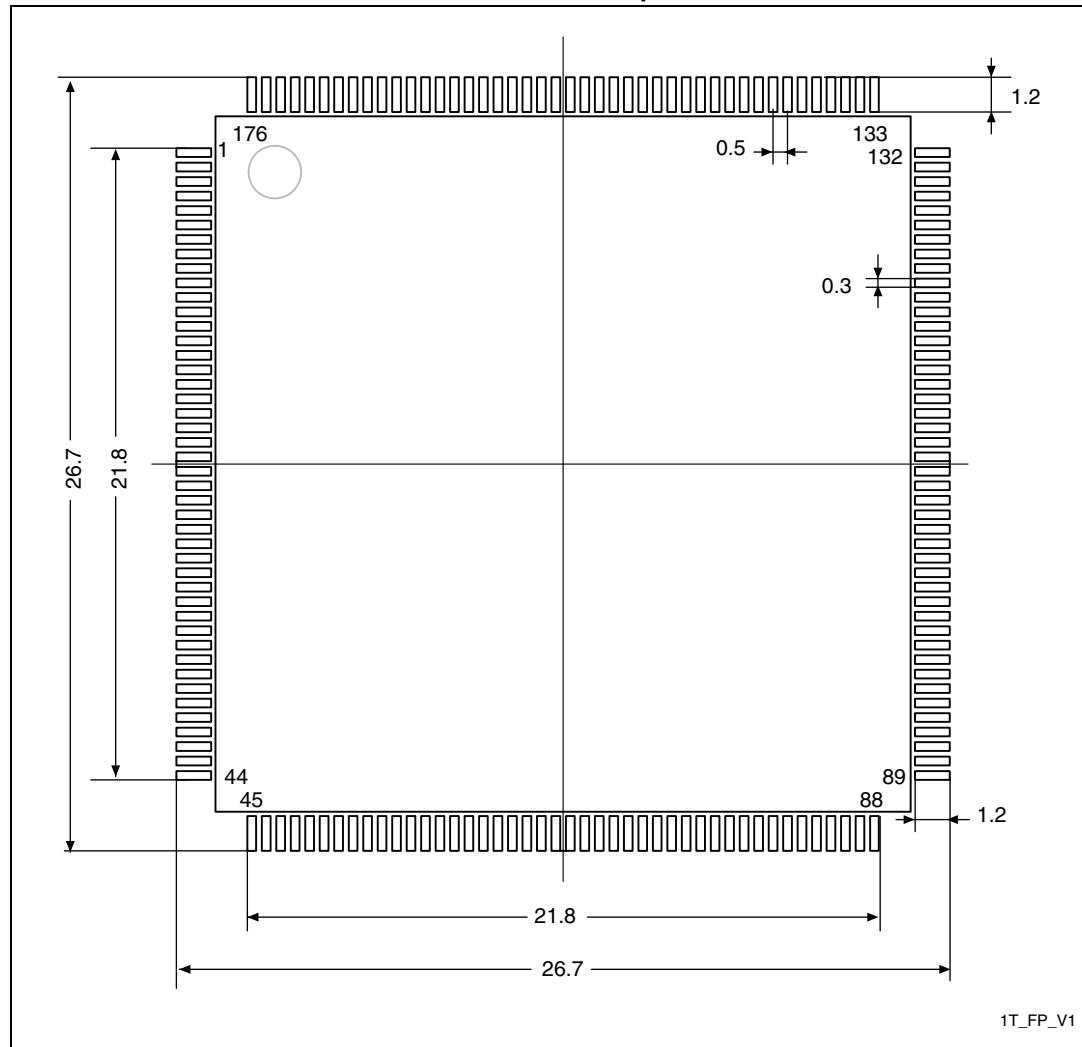
1. Values in inches are converted from mm and rounded to 4 decimal digits.

Figure 82. LQFP100 - 100-pin, 14 x 14 mm low-profile quad flat recommended footprint



1. Dimensions are expressed in millimeters.

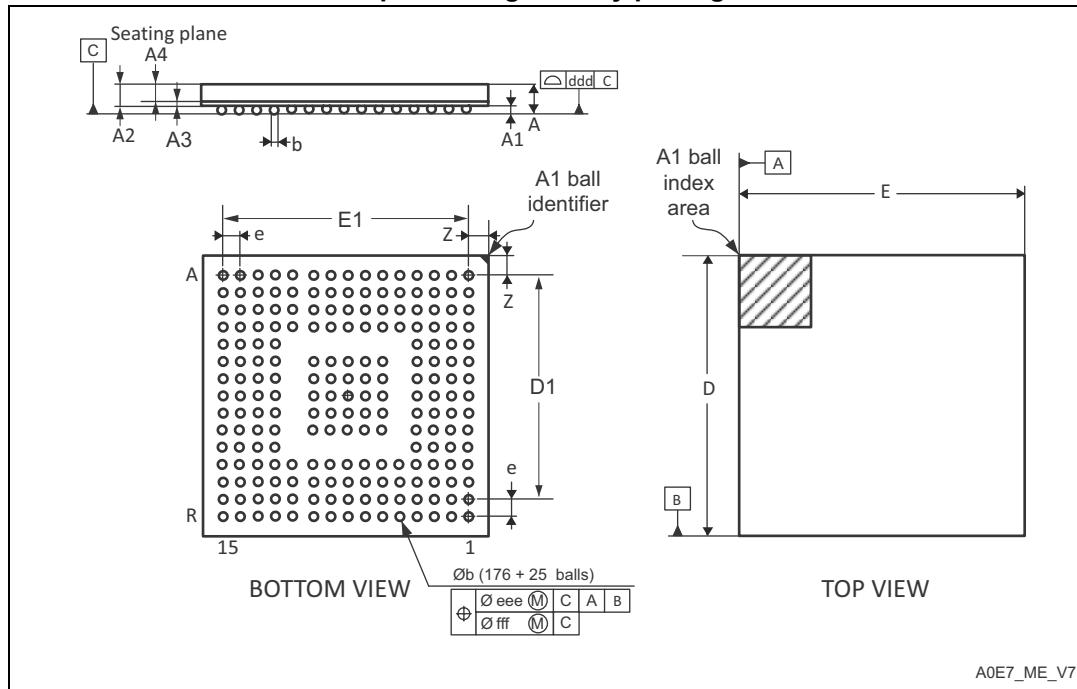
Figure 88. LQFP176 - 176-pin, 24 x 24 mm low profile quad flat package recommended footprint



1. Dimensions are expressed in millimeters.

7.6 UFBGA176+25 package information

Figure 89. UFBGA176+25 - 201-ball, 10 x 10 mm, 0.65 mm pitch, ultra fine pitch ball grid array package outline



1. Drawing is not to scale.

Table 93. UFBGA176+25, - 201-ball, 10 x 10 mm, 0.65 mm pitch, ultra fine pitch ball grid array package mechanical data

Symbol	millimeters			inches ⁽¹⁾		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	-	-	0.600	-	-	0.0236
A1	-	-	0.110	-	-	0.0043
A2	-	0.450	-	-	0.0177	-
A3	-	0.130	-	-	0.0051	0.0094
A4	-	0.320	-	-	0.0126	-
b	0.240	0.290	0.340	0.0094	0.0114	0.0134
D	9.850	10.000	10.150	0.3878	0.3937	0.3996
D1	-	9.100	-	-	0.3583	-
E	9.850	10.000	10.150	0.3878	0.3937	0.3996
E1	-	9.100	-	-	0.3583	-
e	-	0.650	-	-	0.0256	-
Z	-	0.450	-	-	0.0177	-
ddd	-	-	0.080	-	-	0.0031

8 Part numbering

Table 96. Ordering information scheme

Example:

Device family

STM32 = ARM-based 32-bit microcontroller

Product type

F = general-purpose

Device subfamily

205 = STM32F20x, connectivity

207 = STM32F20x, connectivity, camera interface,
Ethernet

Pin count

R = 64 pins or 66 pins⁽¹⁾

V = 100 pins

Z = 144 pins

I = 176 pins

Flash memory size

B = 128 Kbytes of Flash memory

C = 256 Kbytes of Flash memory

E = 512 Kbytes of Flash memory

F = 768 Kbytes of Flash memory

G = 1024 Kbytes of Flash memory

Package

T = LQFP

H = UFBGA

Y = WLCSP

Temperature range

6 = Industrial temperature range, -40 to 85 °C.

7 = Industrial temperature range, -40 to 105 °C.

Software option

Internal code or Blank

Options

xxx = programmed parts

TR = tape and reel

1. The 66 pins is available on WLCSP package only.

For a list of available options (speed, package, etc.) or for further information on any aspect of this device, please contact your nearest ST sales office.